Freescale Semiconductor

MPX4250 Rev 7, 1/2009

Integrated Silicon Pressure Sensor On-Chip Signal Conditioned, Temperature Compensated and Calibrated

The MPX4250 series piezoresistive transducer is a state-of-the-art monolithic silicon pressure sensor designed for a wide range of applications, particularly those employing a microcontroller or microprocessor with A/D inputs. This transducer combines advanced micromachining techniques, thin-film metallization, and bipolar processing to provide an accurate, high-level analog output signal that is proportional to the applied pressure. The small form factor and high reliability of on-chip integration make the Freescale sensor a logical and economical choice for the automotive system engineer.

MPX4250 Series

0 to 250 kPa (0 to 36.3 psi) 0.2 to 4.9 V Output

Application Examples

 Ideally Suited for Microprocessor or Microcontroller-Based Systems

Features

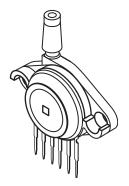
- · Differential and Gauge Applications Available
- 1.4% Maximum Error Over 0° to 85°C
- · Patented Silicon Shear Stress Strain Gauge
- Temperature Compensated Over -40° to +125°C
- · Offers Reduction in Weight and Volume Compared to Existing Hybrid Modules
- · Durable Epoxy Unibody Element

ORDERING INFORMATION									
Device Name	Package	Case No.	# of Ports		Pressure Type		Device Marking		
Device Name	Options		None	Single	Dual	Gauge	Differential	Absolute	Device Marking
Unibody Package (MPX4250 Series)									
MPX4250D	Tray	867	•				•		MPX4250D
MPX4250GP	Tray	867B		•		•			MPX4250GP
MPX4250DP	Tray	867C			•		•		MPX4250DP

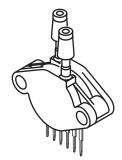
UNIBODY PACKAGES



MPX4250D CASE 867



MPX4250GP CASE 867B



MPX4250DP CASE 867C



Operating Characteristics

Table 1. Operating Characteristics ($V_S = 5.1 \text{ Vdc}$, $T_A = 25 ^{\circ}\text{C}$ unless otherwise noted, P1 > P2. Decoupling circuit shown in Figure 3 required to meet electrical specifications.)

Characteristic		Symbol	Min	Тур	Max	Unit
Pressure Range ⁽¹⁾		P _{OP}	0	_	250	kPa
Supply Voltage ⁽²⁾		V _S	4.85	5.1	5.35	Vdc
Supply Current		Io	_	7.0	10	mAdc
Minimum Pressure Offset @ V _S = 5.1 Volts ⁽³⁾	(0 to 85°C)	V _{off}	0.139	0.204	0.269	Vdc
Full Scale Output @ V _S = 5.1 Volts ⁽⁴⁾	(0 to 85°C)	V _{FSO}	4.844	4.909	4.974	Vdc
Full Scale Span @ V _S = 5.1 Volts ⁽⁵⁾	(0 to 85°C)	V _{FSS}	_	4.705	_	Vdc
Accuracy ⁽⁶⁾	(0 to 85°C)	_	_	_	±1.4	%V _{FSS}
Sensitivity		ΔV/ΔΡ	_	18.8		mV/kPa
Response Time ⁽⁷⁾		t _R	_	1.0		ms
Output Source Current at Full Scale Output		I _{o+}	_	0.1		mAdc
Warm-Up Time ⁽⁸⁾		_	_	20		ms
Offset Stability ⁽⁹⁾		_	_	±0.5		%V _{FSS}

- 1. 1.0 kPa (kiloPascal) equals 0.145 psi.
- 2. Device is ratiometric within this specified excitation range.
- 3. Offset (Voff) is defined as the output voltage at the minimum rated pressure.
- Full Scale Output (V_{FSO}) is defined as the output voltage at the maximum or full rated pressure.
- Full Scale Span (V_{FSS}) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.
- 6. Accuracy (error budget) consists of the following:

Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to

and from the minimum or maximum operating temperature points, with zero differential pressure applied.

Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the

minimum or maximum rated pressure, at 25°C.

TcSpan: Output deviation over the temperature range of 0 to 85°C, relative to 25°C.

TcOffset: Output deviation with minimum rated pressure applied, over the temperature range of 0 to 85°C, relative to 25°C.

Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of V_{FSS}, at 25°C.

- 7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.
- 8. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.
- 9. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

Maximum Ratings

Table 2. Maximum Ratings⁽¹⁾

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P _{MAX}	1000	kPa
Storage Temperature	T _{STG}	-40 to +125	°C
Operating Temperature	T _A	-40 to +125	°C

^{1.} Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.

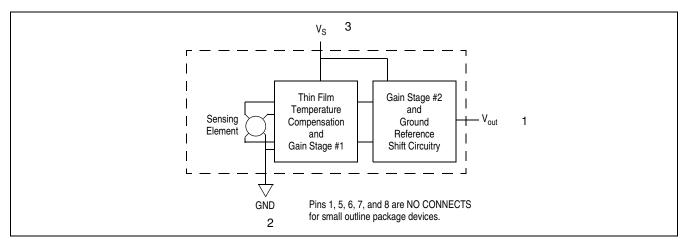


Figure 1. Fully Integrated Pressure Sensor Schematic

On-chip Temperature Compensation and Calibration

Figure 2 illustrates the differential/gauge pressure sensing chip in the basic chip carrier (Case 867). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MPX4250 series pressure sensor operating characteristics and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor

performance and long-term reliability. Contact the factory for information regarding media compatibility in your application.

Figure 3 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller.

Figure 4 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 3. The output will saturate outside of the specified pressure range

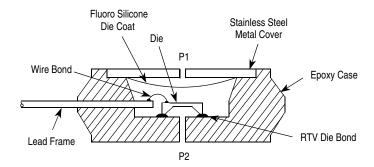


Figure 2. Cross Sectional Diagram (not to scale)

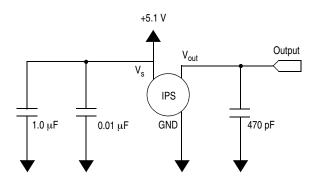


Figure 3. Recommended Power Supply Decoupling and Output Filtering (For additional output filtering, please refer to Application Note AN1535)

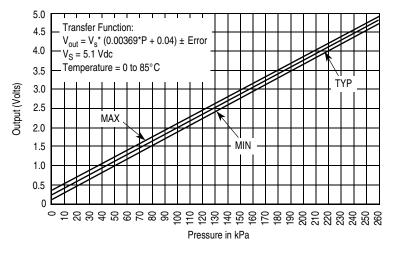
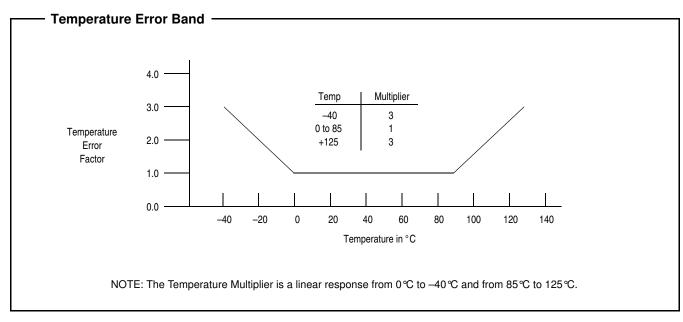


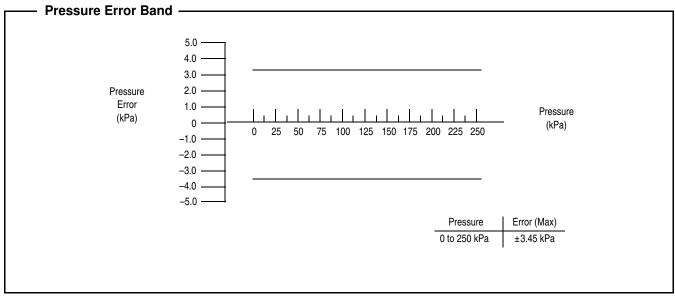
Figure 4. Output versus Absolute Pressure

Transfer Function (MPX4250)

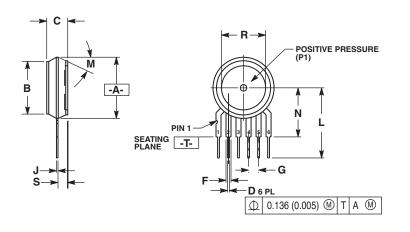
Nominal Transfer Value: $V_{out} = V_S \times (0.00369 \times P + 0.04)$ $\pm (Pressure\ Error\ x\ Temp.\ Factor\ x\ 0.00369 \times V_S)$

 $V_S = 5.1 \pm 0.25 \text{ Vdc}$





PACKAGE DIMENSIONS

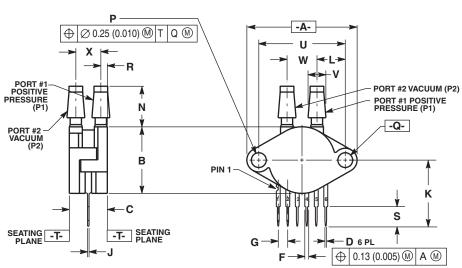


- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

	INC	HES	MILLIMETERS			
DIM	MIN MAX		MIN	MAX		
Α	0.595	0.630	15.11	16.00		
В	0.514	0.534	13.06	13.56		
С	0.200	0.220	5.08	5.59		
D	0.027	0.033	0.68	0.84		
F	0.048	0.064	1.22	1.63		
G	0.100	BSC	2.54 BSC			
7	0.014	0.016	0.36	0.40		
L	0.695	0.725	17.65	18.42		
M	30° NOM		30° NOM			
N	0.475	0.495	12.07	12.57		
R	0.430	0.450	10.92	11.43		
S	0.090	0.105	2.29	2.66		

- STYLE 1: PIN 1. VOUT 2. GROUND 3. VCC 4. V1 5. V2 6. VEX
- STYLE 2:
 PIN 1. OPEN
 2. GROUND
 3. -VOUT
 4. VSUPPLY
 5. +VOUT
 6. OPEN
- STYLE 3:
 PIN 1. OPEN
 2. GROUND
 3. +VOUT
 4. +VSUPPLY
 5. -VOUT
 6. OPEN

BASIC ELEMENT (D) CASE 867-08 ISSUE N



NOTES:

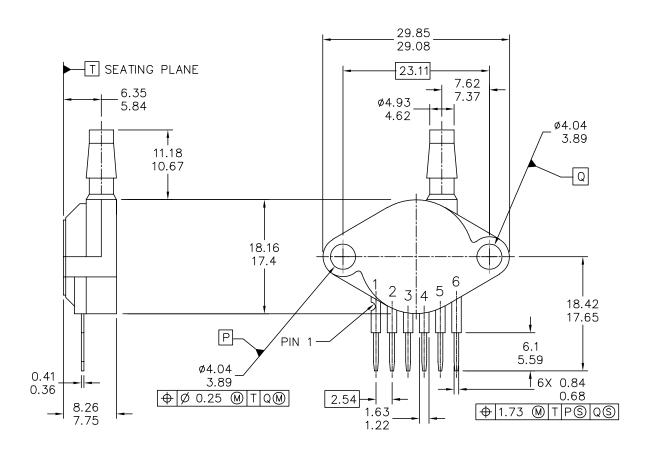
- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	1.145	1.175	29.08	29.85	
В	0.685	0.715	17.40	18.16	
С	0.405	0.435	10.29	11.05	
D	0.027	0.033	0.68	0.84	
F	0.048	0.064	1.22	1.63	
G	0.100	BSC	2.54	BSC	
J	0.014	0.016	0.36	0.41	
K	0.695	0.725	17.65	18.42	
L	0.290	0.300	7.37	7.62	
N	0.420	0.440	10.67	11.18	
Р	0.153	0.159	3.89	4.04	
Q	0.153	0.159	3.89	4.04	
R	0.063	0.083	1.60	2.11	
S	0.220	0.240	5.59	6.10	
U	0.910 BSC		23.11 BSC		
٧	0.182	0.194	4.62	4.93	
W	0.310	0.330	7.87	8.38	
Х	0.248	0.278	6.30	7.06	

STYLE 1: PIN 1. Vout 2. GROUND 3. Vcc 4. V1 5. V2 6. Vex

PRESSURE AND VACUUM SIDE DUAL PORTED (DP) **CASE 867C-05 ISSUE F**

PACKAGE DIMENSIONS



	MECHANICA	L OUTLINE	PRINT VERSION NO	IT TO SCALE
TITLE:	DOCUMENT NO	1: 98ASB42796B	REV: G	
SENSOR, 6 LEAD UNIBO	CASE NUMBER: 867B-04 28 JUL 2005			
AP & GP 01ASB09	STANDARD: NON-JEDEC			

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PRESSURE SIDE PORTED (GP) CASE 867B-04 ISSUE G

MPX4250

PACKAGE DIMENSIONS

NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- 3. 867B-01 THRU -3 OBSOLETE, NEW STANDARD 867B-04.

STYLE 1:

PIN 1: V OUT

2: GROUND 3: VCC 4: V1

5: V2

6: V EX

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TITLE:	DOCUMENT NO: 98ASB42796B REV: G			
SENSOR, 6 LEAD UNIBO	CASE NUMBER: 867B-04 28 JUL 2005			
AP & GP 01ASB09	STANDARD: NO	DN-JEDEC		

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PRESSURE SIDE PORTED (GP) **CASE 867B-04 ISSUE G**

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